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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFl

2 0 0 0 0 0	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	20MHz
Connectivity	IDE/ATAPI, I ² C, Memory Card, PCM, SPI, UART/USART, USB
Peripherals	I ² S, POR, WDT
Number of I/O	44
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2.25K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.3V
Data Converters	A/D 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89c5132-rotul

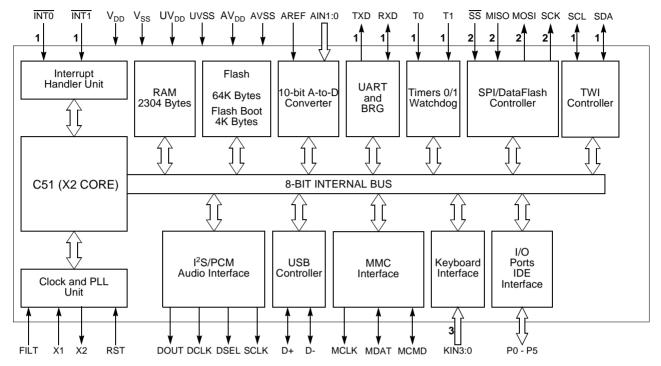
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Block Diagram





- Notes: 1. Alternate function of Port 3
 - 2. Alternate function of Port 4
 - 3. Alternate function of Port 1

Signals

All the AT89C5132 signals are detailed by functionality in Table 1 to Table 15. **Table 1.** Ports Signal Description

Signal Name	Туре	Description	Alternate Function			
P0.7:0	I/O	Port 0P0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1sI/Owritten to them float and can be used as high impedance inputs. To avoid any parasitic current consumption, floating P0 inputs must be polarized to V _{DD} or V _{SS} .				
P1.7:0	I/O	Port 1 P1 is an 8-bit bidirectional I/O port with internal pull-ups.	KIN3:0 SCL SDA			
P2.7:0	I/O	Port 2 P2 is an 8-bit bidirectional I/O port with internal pull-ups.	A15:8			
P3.7:0	Port 3 P3 is an 8-bit bidirectional I/O port with internal pull-ups.		RXD TXD INT0 INT1 T0 T1 WR RD			
P4.7:0	I/O	Port 4 P4 is an 8-bit bidirectional I/O port with internal pull-ups.	MISO MOSI SCK SS			
P5.3:0	I/O	Port 5 P5 is a 4-bit bidirectional I/O port with internal pull-ups.	-			

Table 2. Clock Signal Description

Signal Name	5		Alternate Function
X1	X1Input to the on-chip inverting oscillator amplifier To use the internal oscillator, a crystal/resonator circuit is connected to this pin. If an external oscillator is used, its output is connected to this pin. X1 is the clock source for internal timing.		-
X2	2 O Output of the on-chip inverting oscillator amplifier To use the internal oscillator, a crystal/resonator circuit is connected to this pin. If an external oscillator is used, leave X2 unconnected.		-
FILT	I	PLL Low Pass Filter input FILT receives the RC network of the PLL low pass filter.	-





Table 11. A/D Converter Signal Description

Signal Name	Туре	Description	Alternate Function	
AIN1:0	I	A/D Converter Analog Inputs	-	
AREFP	I	Analog Positive Voltage Reference Input	-	
AREFN	I	Analog Negative Voltage Reference Input This pin is internally connected to AVSS.	-	

Table 12. Keypad Interface Signal Description

Signal Name	Туре	Description	
KIN3:0	I	Keypad Input Lines Holding one of these pins high or low for 24 oscillator periods triggers a keypad interrupt.	P1.3:0

 Table 13.
 External Access Signal Description

Signal Name	Туре	Description	Alternate Function
A15:8	I/O	Address Lines Upper address lines for the external bus. Multiplexed higher address and data lines for the IDE interface.	P2.7:0
AD7:0	I/O	Address/Data Lines Multiplexed lower address and data lines for the external memory or the IDE interface.	P0.7:0
ALE	0	Address Latch Enable Output ALE signals the start of an external bus cycle and indicates that valid address information is available on lines A7:0. An external latch is used to demultiplex the address from address/data bus.	-
ISP	I/O	ISP Enable Input This signal must be held to GND through a pull-down resistor at the falling reset to force execution of the internal bootloader.	-
RD	0	Read Signal Read signal asserted during external data memory read operation.	P3.7
WR	0	Write Signal Write signal asserted during external data memory write operation.	P3.6

Table 14. System Signal Description

Signal Name			Alternate Function
RST	T	Reset Input Holding this pin high for 64 oscillator periods while the oscillator is running resets the device. The Port pins are driven to their reset conditions when a voltage lower than V_{IL} is applied, whether or not the oscillator is running. This pin has an internal pull-down resistor which allows the device to be reset by connecting a capacitor between this pin and V_{DD} . Asserting RST when the chip is in Idle mode or Power-Down mode returns the chip to normal operation.	-
TST	Ι	Test Input Test mode entry signal. This pin must be set to $V_{\text{DD}}.$	-

Table 15. Power Signal Description	1
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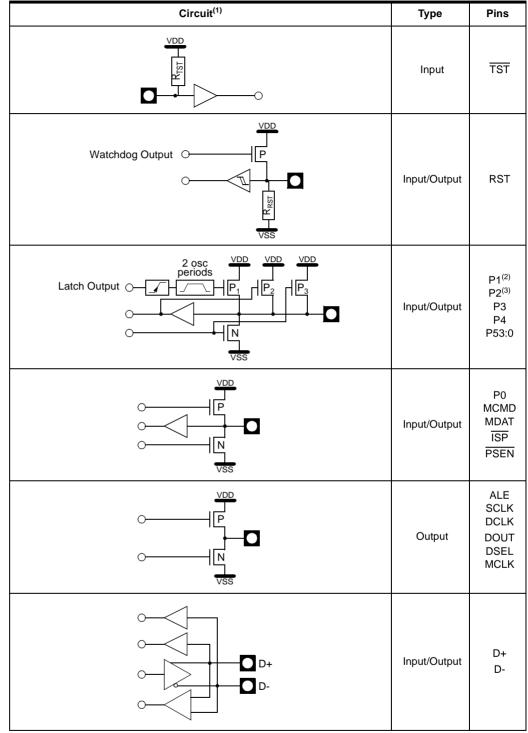
Signal Name	Туре	Description	Alternate Function
VDD	PWR	Digital Supply Voltage Connect these pins to +3V supply voltage.	-
VSS	GND	Circuit Ground Connect these pins to ground.	-
AVDD	PWR	Analog Supply Voltage Connect this pin to +3V supply voltage.	-
AVSS	GND	Analog Ground Connect this pin to ground.	-
PVDD	PWR	PLL Supply voltage Connect this pin to +3V supply voltage.	-
PVSS	GND	PLL Circuit Ground Connect this pin to ground.	-
UVDD	PWR	USB Supply Voltage Connect this pin to +3V supply voltage.	-
UVSS	GND	USB Ground Connect this pin to ground.	-





Internal Pin Structure

 Table 16.
 Detailed Internal Pin Structure



Notes: 1. For information on resistors value, input/output levels, and drive capability, refer to the Section "DC Characteristics", page 183.

^{2.} When the Two Wire controller is enabled, P₁, P₂, and P₃ transistors are disabled allowing pseudo open-drain structure.

^{3.} In Port 2, P₁ transistor is continuously driven when outputting a high level bit address (A15:8).

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(8)

Peripherals

The AT8xC5132 peripherals are briefly described in the following sections. For further details on how to interface (hardware and software) to these peripherals, please refer to the AT8xC5132 complete datasheet.

- **Clock Generator System** The AT8xC5132 internal clocks are extracted from an on-chip PLL fed by an on-chip oscillator. Four clocks are generated respectively for the C51 core, the audio interface, and the other peripherals. The C51 and peripheral clocks are derived from the oscillator clock. The audio interface sample rates are also obtained by dividing the PLL output clock.
- PortsThe AT8xC5132 implement five 8-bit ports (P0 to P4) and one 4-bit port (P5). In addition
to performing general-purpose I/Os, some ports are capable of external data memory
operations; others allow for alternate functions. All I/O Ports are bidirectional. Each Port
contains a latch, an output driver and an input buffer. Port 0 and Port 2 output drivers
and input buffers facilitate external memory operations. Some Port 1, Port 3 and Port 4
pins serve for both general-purpose I/Os and alternate functions.
- **Timers/Counters** The AT8xC5132 implement the two general-purpose, 16-bit Timers/Counters of a standard C51. They are identified as Timer 0, Timer 1, and can independently be configured each to operate in a variety of modes as a Timer or as an event Counter. When operating as a Timer, a Timer/Counter runs for a programmed length of time, then issues an interrupt request. When operating as a Counter, a Timer/Counter counts negative transitions on an external pin. After a preset number of counts, the Counter issues an interrupt request.
- Watchdog TimerThe AT8xC5132 implement a hardware Watchdog Timer that automatically resets the
chip if it is allowed to time out. The WDT provides a means of recovering from routines
that do not complete successfully due to software or hardware malfunctions.
- Audio Output Interface The AT8xC5132 implements an audio output interface allowing the decoded audio bitstream to be output in various formats. They are compatible with right and left justification PCM and I₂S formats and the on-chip PLL allows connection of almost all commercial audio DAC families available on the market.

Universal Serial BusThe AT8xC5132 implements a full-speed Universal Serial Bus Interface. The USB inter-
face can be used for the following purposes:

- Download of files by supporting the USB mass storage class.
- In-System Programming by supporting the USB firmware upgrade class.
- MultiMedia CardThe AT8xC5132 implements a MultiMedia Card (MMC) interface compliant to the V2.2Interfacespecification in MultiMedia Card mode. The MMC allows storage of files in removable
Flash memory cards that can be easily plugged or removed from the application. It can
also be used for In-System Programming.
- **IDE/ATAPI Interface** The AT8xC5132 provide an IDE/ATAPI interface allowing connection of devices such as CD-ROM reader, CompactFlash™ cards, Hard Disk Drive, etc. It consists of a 16-bit bidirectional bus part of the low-level ANSI ATA/ATAPI specification. It is provided for mass storage interface but could be used for In-System Programming using CD-ROM.

Electrical Characteristics

Absolute Maximum Ratings

Storage Temperature	65°C to +150°C
Voltage on any other Pin to $V_{\mbox{\scriptsize SS}}$	-0.3 to +4.0V
I _{OL} per I/O Pin	5 mA
Power Dissipation	1 W
Ambient Temperature Under Bias	40°C to +85°C
V _{DD}	2.7V to 3.3V

NOTE: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "operating conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

DC Characteristics

Digital Logic

Table 1. Digital DC Characteristics $V_{DD} = 2.7$ to 3.3V , $T_A = -40^{\circ}$ to +85°C

Symbol	Parameter	Min	Typ ⁽¹⁾	Max	Units	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2·V _{DD} - 0.1	V	
V _{IH1}	Input High Voltage (except RST, X1)	0.2·V _{DD} + 1.1		V _{DD}	V	
$V_{\rm IH2}$	Input High Voltage (RST, X1)	0.7·V _{DD} ⁽²⁾		V _{DD} + 0.5	V	
V _{OL1}	Output Low Voltage (except P0, ALE, MCMD, MDAT, MCLK, SCLK, DCLK, DSEL, DOUT)			0.45	V	I _{OL} = 1.6 mA
V _{OL2}	Output Low Voltage (P0, ALE, MCMD, MDAT, MCLK, SCLK, DCLK, DSEL, DOUT)			0.45	V	I _{OL} = 3.2 mA
V _{OH1}	Output High Voltage (P1, P2, P3, P4 and P5)	V _{DD} - 0.7			V	I _{OH} = -30 μA
V _{OH2}	Output High Voltage (P0, P2 address mode, ALE, MCMD, MDAT, MCLK, SCLK, DCLK, DSEL, DOUT, D+, D-)	V _{DD} - 0.7			v	I _{OH} = -3.2 mA
I _{IL}	Logical 0 Input Current (P1, P2, P3, P4 and P5)			-50	μΑ	Vin = 0.45 V

Table 1. Digital DC Characteristics $V_{DD} = 2.7 \text{ to } 3.3 \text{V}$, $T_A = -40^\circ \text{ to } +85^\circ \text{C}$

Symbol	Parameter	Min	Typ ⁽¹⁾	Max	Units	Test Conditions
ILI	Input Leakage Current (P0, ALE, MCMD, MDAT, MCLK, SCLK, DCLK, DSEL, DOUT)			10	μA	0.45< V _{IN} < V _{DD}
I _{TL}	Logical 1 to 0 Transition Current (P1, P2, P3, P4 and P5)			-650	μΑ	Vin = 2.0 V
R _{RST}	Pull-Down Resistor	50	90	200	kΩ	
CIO	Pin Capacitance		10		pF	$T_A = 25^{\circ}C$
V_{RET}	V _{DD} Data Retention Limit			1.8	V	
I _{DD}	Operating Current		(3)	X1 / X2 mode 6.5 / 10.5 8 / 13.5 9.5 / 17	mA	V _{DD} < 3.3 V 12 MHz 16 MHz 20 MHz
I _{DL}	Idle Mode Current		(3)	X1 / X2 mode 5.3 / 8.1 6.4 / 10.3 7.5 / 13	mA	V _{DD} < 3.3 V 12 MHz 16 MHz 20 MHz
I _{PD}	Power-Down Mode Current		20	500	μA	V _{RET} < V _{DD} < 3.3 V

Notes: 1. Typical values are obtained using V_{DD} = 3 V and T_A = 25°C. They are not tested and there is no guarantee on these values.

2. Flash retention is guaranteed with the same formula for V_{DD} min down to 0V.

3. See Table 154 for typical consumption in player mode.



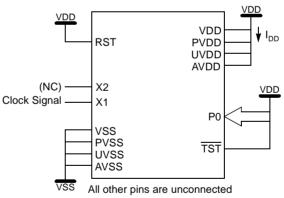






Figure 2. I_{DL} Test Condition, Idle Mode

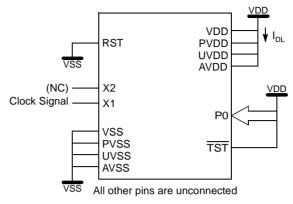
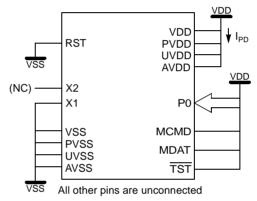


Figure 3. I_{PD} Test Condition, Power-Down Mode



A-to-D Converter

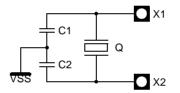
Table 2. A-to-D Converter DC Characteristics $V_{DD} = 2.7$ to 3.3V, $T_A = -40^{\circ}$ C to $+85^{\circ}$ C

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
AV_{DD}	Analog Supply Voltage	2.7		3.3	V	
AI _{DD}	Analog Operating Supply Current			600	μA	$AV_{DD} = 3.3V$ AIN1:0 = 0 to AV_{DD}
AI _{PD}	Analog Standby Current			2	μA	AV _{DD} = 3.3V ADEN = 0 or PD = 1
AV _{IN}	Analog Input Voltage	AV_{SS}		AV_{DD}	V	
AV _{REF}	Reference Voltage A _{REFN} A _{REFP}	AV _{SS} 2.4		aV _{dd}	V V	
R_{REF}	AREF Input Resistance	10		30	kΩ	$T_A = 25^{\circ}C$
C _{IA}	Analog Input capacitance			10	pF	$T_A = 25^{\circ}C$

Oscillator and Crystal

Schematic

Figure 4. Crystal Connection



Note: For operation with most standard crystals, no external components are needed on X1 and X2. It may be necessary to add external capacitors on X1 and X2 to ground in special cases (max 10 pF). X1 and X2 may not be used to drive other circuits.

Parameters

Table 3. Oscillator and Crystal Characteristics V/ 2.7 to 2.2 V/

 V_{DD} = 2.7 to 3.3V , T_A = -40° to +85°C

Symbol	Parameter	Min	Тур	Max	Unit
C _{X1}	Internal Capacitance (X1 - V _{SS})		10		pF
C _{X2}	Internal Capacitance (X2 - V _{SS})		10		pF
CL	Equivalent Load Capacitance (X1 - X2)		5		pF
DL	Drive Level			50	μW
F	Crystal Frequency			20	MHz
RS	Crystal Series Resistance			40	Ω
CS	Crystal Shunt Capacitance			6	pF

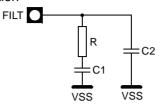




Phase Lock Loop

Schematic

Figure 5. PLL Filter Connection



Parameters

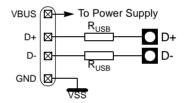
Table 4. PLL Filter Characteristics V_{DD} = 2.7 to 3.3V , T_A = -40° to +85°C

Symbol	Parameter	Min	Тур	Max	Unit
R	Filter Resistor		100		Ω
C1	Filter Capacitance 1		10		nF
C2	Filter Capacitance 2		2.2		nF

USB Connection

Schematic

Figure 6. USB Connection



Parameters

Table 1. USB Termination Characteristics

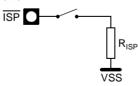
 V_{DD} = 2.7 to 3.3 V, T_{A} = -40 to +85°C

Symbol	Parameter	Min	Тур	Max	Unit
R_{USB}	USB Termination Resistor		27		Ω

In-system Programming

Schematic

Figure 7. ISP Pull-down Connection



Parameters

Table 5. ISP Pull-Down Characteristics V_{DD} = 2.7 to 3.3V , T_{A} = -40° to +85°C

Symbol	Parameter	Min	Тур	Max	Unit
R _{ISP}	ISP Pull-Down Resistor		2.2		kΩ

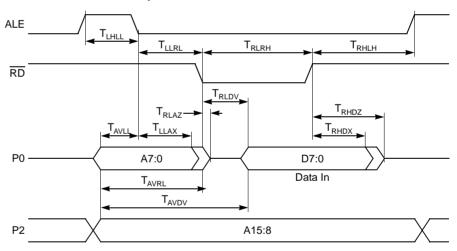


Table 3. External 8-bit Bus Cycle – Data Write AC Timings V_{DD} = 2.7 to 3.3V, T_A = -40° to +85°C

		Variable Standar		Variable Clock X2 Mode		
Symbol	Parameter	Min	Max	Min	Max	Unit
T _{CLCL}	Clock Period	50		50		ns
T _{LHLL}	ALE Pulse Width	2·T _{CLCL} -15		T _{CLCL} -15		ns
T _{AVLL}	Address Valid to ALE Low	T _{CLCL} -20		0.5·T _{CLCL} -20		ns
T _{LLAX}	Address hold after ALE Low	T _{CLCL} -20		0.5·T _{CLCL} -20		ns
T _{LLWL}	ALE Low to WR Low	3-T _{CLCL} -30		1.5·T _{CLCL} -30		ns
T _{WLWH}	WR Pulse Width	6·T _{CLCL} -25		3.T _{CLCL} -25		ns
T_{WHLH}	WR High to ALE High	T _{CLCL} -20	T _{CLCL} +20	0.5·T _{CLCL} -20	0.5·T _{CLCL} +20	ns
T _{AVWL}	Address Valid to WR Low	4.T _{CLCL} -30		2.T _{CLCL} -30		ns
T _{QVWH}	Data Valid to WR High	7.T _{CLCL} -20		3.5·T _{CLCL} -20		ns
T _{WHQX}	Data Hold after WR High	T _{CLCL} -15		0.5·T _{CLCL} -15		ns

Waveforms

Figure 1. External 8-bit Bus Cycle - Data Read Waveforms





Timings

Table 8. SPI Interface Master AC Timing V_{DD} = 2.7 to 3.3V, T_A = -40° to +85°C

Symbol	Parameter	Min	Мах	Unit
	Slave Mode	1		
Т _{снсн}	Clock Period	8		T _{osc}
Т _{снсх}	Clock High Time	3.2		T _{OSC}
T _{CLCX}	Clock Low Time	3.2		T _{OSC}
T _{SLCH} , T _{SLCL}	SS Low to Clock edge	200		ns
T _{IVCL} , T _{IVCH}	Input Data Valid to Clock Edge	100		ns
T _{CLIX} , T _{CHIX}	Input Data Hold after Clock Edge	100		ns
T _{CLOV,} T _{CHOV}	Output Data Valid after Clock Edge		100	ns
T _{CLOX} , T _{CHOX}	Output Data Hold Time after Clock Edge	0		ns
T _{CLSH} , T _{CHSH}	SS High after Clock Edge	0		ns
T _{IVCL} , T _{IVCH}	Input Data Valid to Clock Edge	100		ns
T _{CLIX} , T _{CHIX}	Input Data Hold after Clock Edge	100		ns
T _{SLOV}	SS Low to Output Data Valid		130	ns
T _{SHOX}	Output Data Hold after SS High		130	ns
T _{SHSL}	SS High to SS Low	(1)		
T _{ILIH}	Input Rise Time		2	μs
T _{IHIL}	Input Fall Time		2	μs
Т _{оloн}	Output Rise Time		100	ns
Т _{ОНОL}	Output Fall Time		100	ns
	Master Mode	•	•	1
Т _{снсн}	Clock Period	4		T _{OSC}
Т _{снсх}	Clock High Time	1.6		T _{OSC}
T _{CLCX}	Clock Low Time	1.6		T _{OSC}
T _{IVCL} , T _{IVCH}	Input Data Valid to Clock Edge	50		ns
T _{CLIX} , T _{CHIX}	Input Data Hold after Clock Edge	50		ns
T _{CLOV,} T _{CHOV}	Output Data Valid after Clock Edge		65	ns
T _{CLOX} , T _{CHOX}	Output Data Hold Time after Clock Edge	0		ns
T _{ILIH}	Input Data Rise Time		2	μs
T _{IHIL}	Input Data Fall Time		2	μs
Т _{оloн}	Output Data Rise Time		50	ns
T _{OHOL}	Output Data Fall Time		50	ns

Notes: 1. Value of this parameter depends on software.

2. Test conditions: capacitive load on all pins = 100 pF

Waveforms

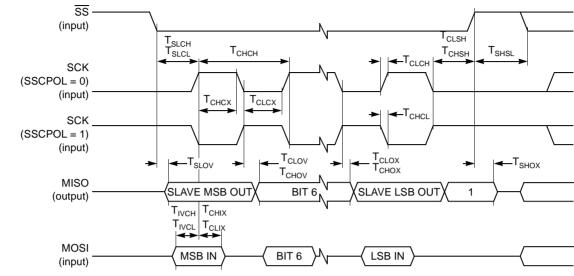
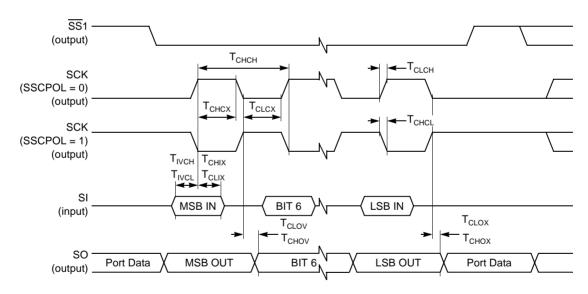


Figure 5. SPI Slave Waveforms (SSCPHA = 0)



Figure 6. SPI Slave Waveforms (SSCPHA = 1)



Note: 1. Not Defined but generally the LSB of the character which has just been received.





MMC Interface

Definition of Symbols

Table 9. MMC Interface Timing Symbol Definitions

Signals				
С	Clock			
D	Data In			
0	Data Out			

Conditions				
Н	High			
L	Low			
V	Valid			
Х	No Longer Valid			

Timings

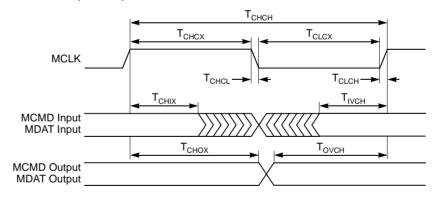
Table 10. MMC Interface AC Timings

V_{DD} = 2.7 to 3.3 V, T_{A} = -40 to +85°C, CL \leq 100pF (10 cards)

Symbol	Parameter	Min	Max	Unit
Т _{снсн}	Clock Period	50		ns
T _{CHCX}	Clock High Time	10		ns
T _{CLCX}	Clock Low Time	10		ns
T _{CLCH}	Clock Rise Time		10	ns
T _{CHCL}	Clock Fall Time		10	ns
T _{DVCH}	Input Data Valid to Clock High	3		ns
T _{CHDX}	Input Data Hold after Clock High	3		ns
T _{CHOX}	Output Data Hold after Clock High	5		ns
T _{OVCH}	Output Data Valid to Clock High	5		ns

Waveforms

Figure 10. MMC Input Output Waveforms



Audio Interface

Definition of Symbols

 Table 11.
 Audio Interface Timing Symbol Definitions

Signals				
С	Clock			
0	Data Out			
S	Data Select			

Conditions			
Н	High		
L	Low		
V	Valid		
х	No Longer Valid		

Timings

Table 12. Audio Interface AC timings

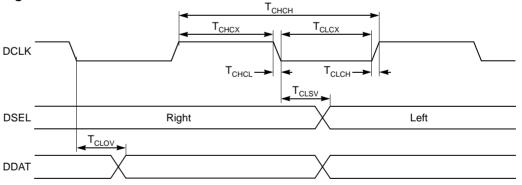
V_{DD} = 2.7 to 3.3V, T_A = -40 to +85°C, $CL \leq 30 p F$

Symbol	Parameter	Min	Max	Unit
Тснсн	Clock Period		325.5 ⁽¹⁾	ns
T _{CHCX}	Clock High Time	30		ns
T _{CLCX}	Clock Low Time	30		ns
T _{CLCH}	Clock Rise Time		10	ns
T _{CHCL}	Clock Fall Time		10	ns
T _{CLSV}	Clock Low to Select Valid		10	ns
T _{CLOV}	Clock Low to Data Valid		10	ns

Note: 32-bit format with Fs = 48 kHz.

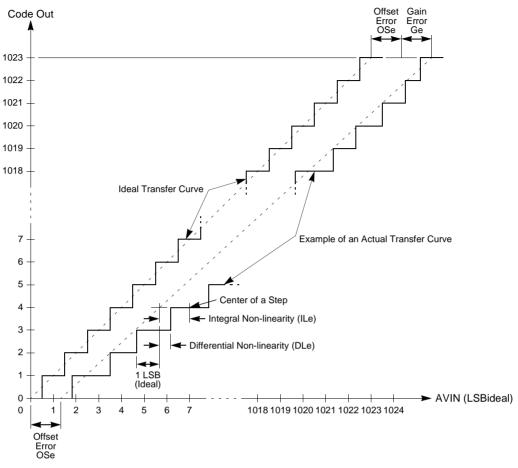
Waveforms

Figure 11. Audio Interface Waveforms









Flash Memory

Definition of Symbols

Table 14. Flash Memory Timing Symbol Definitions

Signals			
s	ISP		
R	RST		
В	FBUSY flag		

Conditions			
L	Low		
V	Valid		
х	No Longer Valid		

Timings

Table 15. Flash Memory AC Timing

 V_{DD} = 2.7 to 3.3V, T_A = -40° to +85°C

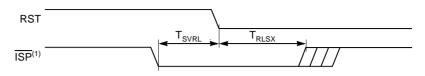
Symbol	Parameter	Min	Тур	Max	Unit
T _{SVRL}	Input ISP Valid to RST Edge	50			ns
T _{RLSX}	Input ISP Hold after RST Edge	50			ns
T _{BHBL}	FLASH Internal Busy (Programming) Time		10		ms
N _{FCY}	Number of Flash Write Cycles	100K			Cycle
T _{FDR}	Flash Data Retention Time	10			Year







Figure 14. Flash Memory – ISP Waveforms



Note: 1. ISP must be driven through a pull-down resistor (see Section "In-system Programming", page 22).

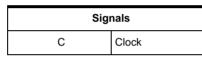
Figure 15. Flash Memory – Internal Busy Waveforms



External Clock Drive and Logic Level References

Definition of Symbols

 Table 16.
 External Clock Timing Symbol Definitions



Conditions				
н	High			
L	Low			
Х	No Longer Valid			

Timings

Table 17. External Clock AC Timings

 V_{DD} = 2.7 to 3.3V, T_A = -40 to +85°C

Symbol	Parameter	Min	Max	Unit
T _{CLCL}	Clock Period	50		ns
T _{CHCX}	High Time	10		ns
T _{CLCX}	Low Time	10		ns
T _{CLCH}	Rise Time	3		ns
T _{CHCL}	Fall Time	3		ns
T _{CR}	Cyclic Ratio in X2 Mode	40	60	%

Waveforms

Figure 16. External Clock Waveform

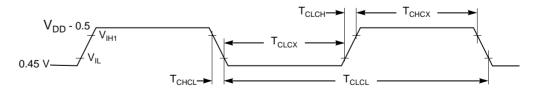
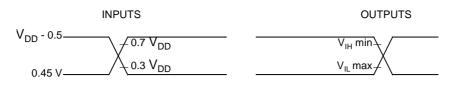


Figure 17. AC Testing Input/Output Waveforms



Notes: 1. During AC testing, all inputs are driven at V_{DD} -0.5V for a logic 1 and 0.45V for a logic 0. 2. Timing measurements are made on all outputs at V_{IH} min for a logic 1 and V_{IL} max for a logic 0.

Figure 18. Float Waveforms



Note: For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loading V_{OH}/V_{OL} level occurs with $I_{OL}/I_{OH} = \pm 20$ mA.





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